# SKM 200 MLI 066 T



SEMITRANS<sup>®</sup> 5

### **Trench IGBT Modules**

SKM 200 MLI 066 T

Target Data

#### Features

- Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CE(sat)</sub> with positive temperature coefficient
- Integrated NTC temperature sensor

#### **Typical Applications**

- UPS
- 3 Level Inverter

#### Remarks

 Case temperature limited to T<sub>c</sub> =125°C max, recommended T<sub>op</sub> = -40..+150°C

Absolute	Maximum Ratings	T <sub>case</sub> =	T <sub>case</sub> = 25°C, unless otherwise specifie				
Symbol Conditions			Values	Units			
IGBT							
V <sub>CES</sub>	T <sub>j</sub> = 25 °C T <sub>j</sub> = 175 °C		600	V			
I <sub>C</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C	280	А			
		T <sub>c</sub> = 80 °C	210	А			
I <sub>CRM</sub>	I <sub>CRM</sub> =2xI <sub>Cnom</sub>		400	А			
V <sub>GES</sub>			± 20	V			
t <sub>psc</sub>	$V_{CC}$ = 360 V; $V_{GE} \le 15$ V; VCES < 600 V	T <sub>j</sub> = 150 °C	6	μs			
Inverse D	Diode						
I <sub>F</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C	270	А			
		T <sub>c</sub> = 80 °C	200	А			
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		400	А			
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; half sine wave	T <sub>j</sub> = 150 °C	1310	А			
Freewhee	eling Diode						
I <sub>F</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C	270	А			
		T <sub>c</sub> = 80 °C	200	А			
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		400	А			
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; half sine wave	T <sub>j</sub> = 150 °C	1310	А			
Module			·				
I <sub>t(RMS)</sub>			500	А			
T <sub>vj</sub>			- 40 + 175	°C			
T <sub>stg</sub>			- 40 + 125	°C			
V <sub>isol</sub>	AC, 1 min.		2500	V			

Characteristics T <sub>case</sub> =			25°C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units	
IGBT	_						
V <sub>GE(th)</sub>	$V_{GE}$ = $V_{CE}$ , $I_C$ = 3,2 mA		5	5,8	6,5	V	
I <sub>CES</sub>	$V_{GE}$ = 0 V, $V_{CE}$ = $V_{CES}$	T <sub>j</sub> = 25 °C			0,01	mA	
I <sub>GES</sub>	V <sub>CE</sub> = 0 V, V <sub>GE</sub> = 20 V	T <sub>j</sub> = 25 °C			1200	nA	
V <sub>CE0</sub>		T <sub>j</sub> = 25 °C		0,9	1	V	
		T <sub>j</sub> = 150 °C		0,7	0,8	V	
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		2,7	4,5	mΩ	
		T <sub>j</sub> = 150°C		5	6,5	mΩ	
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 200 A, V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C <sub>chiplev.</sub>		1,45	1,9	V	
		$T_j = 150^{\circ}C_{chiplev.}$		1,7	2,1	V	
C <sub>ies</sub>				12,3		nF	
C <sub>oes</sub>	V <sub>CE</sub> = 25, V <sub>GE</sub> = 0 V	f = 1 MHz		0,76		nF	
C <sub>res</sub>				0,36		nF	
R <sub>Gint</sub>	$T_j = °C$			1		Ω	
t <sub>d(on)</sub>						ns	
t <sub>r</sub> E <sub>on</sub>	R <sub>Gon</sub> = 2,4 Ω	$V_{\rm CC} = 300V$				ns	
E <sub>on</sub>	R <sub>Goff</sub> = 2,4 Ω	I <sub>C</sub> = 200A T <sub>i</sub> = 150 °C				mJ ns	
t <sub>d(off)</sub> t <sub>f</sub>	Gott -, · · ·	V <sub>GE</sub> = -8V/+15V				ns	
Ч Е <sub>оff</sub>		GL				mJ	
R <sub>th(j-c)</sub>	per IGBT	1		0,21		K/W	



MLI-T

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Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	ode					
$V_F = V_{EC}$	$I_{Fnom}$ = 200 A; $V_{GE}$ = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,4	1,6	V
		T <sub>j</sub> = 150 °C <sub>chiplev.</sub> T <sub>i</sub> = 25 °C		1,4	1,6	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C		0,95	1	V
		T <sub>j</sub> = 150 °C		0,85	0,9	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		2	3	mΩ
		T <sub>j</sub> = 150 °C T <sub>i</sub> = 150 °C		2,7	3,5	mΩ
I <sub>RRM</sub> Q <sub>rr</sub>	I <sub>F</sub> = 200 A	T <sub>j</sub> = 150 °C				A µC
E <sub>rr</sub>	V <sub>GE</sub> = -8 V; V <sub>CC</sub> = 300 V					mJ
R <sub>th(j-c)D</sub>	per diode			0,39		K/W
Free-whe	eling diode (Neutral (	Clamp Diode)				
V <sub>F</sub> = V <sub>EC</sub>	I <sub>Fnom</sub> = 200 A; V <sub>GE</sub> = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,4	1,6	V
		$T_j = 150 \ ^{\circ}C_{chiplev.}$		1,4	1,6	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C		0,95	1	V
		T <sub>j</sub> = 150 °C		0,85	0,9	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		2	3	V
		T <sub>j</sub> = 150 °C		2,7	3,5	V
I <sub>RRM</sub>	I <sub>F</sub> = 200 A	T <sub>j</sub> = 150 °C				А
Q <sub>rr</sub>						μC
E <sub>rr</sub>	$V_{GE} = 0 V; V_{CC} = 600 V$					mJ
R <sub>th(j-c)FD</sub>	per diode			0,39		K/W
M <sub>s</sub>	to heat sink M6		3		5	Nm
M <sub>t</sub>	to terminals M6		2,5		5	Nm
w					310	g
Temperat	ture sensor					
R <sub>100</sub>	T <sub>s</sub> =100°C (R <sub>25</sub> =5kΩ)			493±5%		Ω
						к

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



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